



<b>INFORMATION DISCLOSURE CITATION IN AN APPLICATION</b>  				ATTY. DOCKET NO. 004066 USA/Consilium/Consilium		SERIAL NO. 09/363,966  <div style="text-align: center; font-weight: bold; font-size: 1.2em;">RECEIVED</div> <div style="text-align: center;">JAN 03 2003</div>	
				APPLICANT <b>Technology Center 2100</b> John F. ARACKAPARAMBIL et al.			
				FILING DATE July 29, 1999		GROUP 2125	
U.S. PATENT DOCUMENTS							
EXAMINER'S INITIALS	PUBLICATION / PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
SMB	5,270,222	12/14/93	Moslehi			12/31/90	
SMB	5,375,064	12/20/94	Bollinger			12/02/93	
SMB	5,599,423	02/04/97	Parker et al.			06/30/95	
SMB	5,844,554	12/01/98	Geller et al.			09/17/96	
FOREIGN PATENT DOCUMENTS							
EXAMINER'S INITIALS	PUBLICATION / PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
SMB	WO 95/34866	12/21/95	WO			X	
SMB	WO 98/45090	10/15/98	WO			X	
SMB	EP 0 881 040 A2	12/02/98	Europe			X	
SMB	WO 99/25520	05/27/99	WO			X	
SMB	WO 00/54325	09/14/00	WO			X	
SMB	EP 1 066 925 A2	01/10/01	Europe			X	
SMB	EP 1 092 505 A2	04/18/01	Europe			X	
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)							
SMB	Hu, Albert, Kevin Nguyen, Steve Wong, Xiuhua Zhang, Emanuel Sachs, and Peter Renteln. 1993. "Concurrent Deployment of Run by Run Controller Using SCC Framework." IEEE/SEMI International Semiconductor Manufacturing Science Symposium. pp. 126-132.						
SMB	Hu, Albert, He Du, Steve Wong, Peter Renteln, and Emanuel Sachs. 1994. "Application of Run by Run Controller to the Chemical-Mechanical Planarization Process." IEEE/CPMT International Electronics Manufacturing Technology Symposium. pp. 371-378.						
SMB	Smith, Taber, Duane Boning, James Moyne, Arnon Hurwitz, and John Curry. June 1996: "Compensating for CMP Pad Wear Using Run by Run Feedback Control." Proceedings of the Thirteenth International VLSI Multilevel Interconnection Conference. pp. 437-439.						
SMB	Suzuki, Junichi, and Yoshikazu Yamamoto. 1998. "Toward the Interoperable Software Design Models: Quartet of UML, XML, DOM and CORBA." Proceedings IEEE International Software Engineering Standards Symposium. pp. 1-10.						
SMB	Klein, Bruce. June 1999. "Application Development: XML Makes Object Models More Useful." Informationweek. pp. 1A-6A.						
EXAMINER  <div style="text-align: center; font-size: 1.5em;">SMB</div>				DATE CONSIDERED <div style="text-align: center; font-size: 1.5em;">9/16/04</div> <div style="text-align: center; font-size: 1.5em;">5/28/03</div>			

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.

<b>INFORMATION DISCLOSURE CITATION IN AN APPLICATION</b>   (PTO-1449)	ATTY. DOCKET NO. 004066 USA/Consilium/Consilium	SERIAL NO. 09/363,966  <div style="text-align: center; border: 1px solid black; padding: 5px;"> <b>RECEIVED</b>             JAN 03 2003             Technology Center 2100         </div>
	APPLICANT John F. ARACKAPARAMBIL et al.	
	FILING DATE July 29, 1999	GROUP 2125

**U.S. PATENT DOCUMENTS**

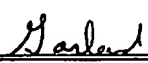
EXAMINER'S INITIALS	PUBLICATION / PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
SRG	5,889,991	03/30/99	Consolatti et al.			12/06/96
SRG	6,183,345 B1	02/06/01	Kamono et al.			03/20/98
SRG	6,253,366 B1	06/26/01	Mutschler, III			03/31/99
SRG	6,298,470 B1	10/02/01	Breiner et al.			04/15/99

**FOREIGN PATENT DOCUMENTS**


EXAMINER'S INITIALS	PUBLICATION / PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
SRG	WO 01/52055 A3	07/19/01	WO			X	
SRG	WO 01/57823 A2	08/09/01	WO			X	
SRG	EP 1 182 526 A2	02/27/02	Europe			X	
SRG	WO 02/17150 A1	02/28/02	WO			X	
SRG	WO 02/33737 A2	04/25/02	WO			X	

**OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)**

SRG	Chemali, Chadi El, James Moyne, Kareemullah Khan, Rock Nadeau, Paul Smith, John Colt, Jonathan Chapple-Sokol, and Tarun Parikh. July/August 2000. "Multizone Uniformity Control of a Chemical Mechanical Polishing Process Utilizing a Pre- and Postmeasurement Strategy." J. Vac. Sci. Technol. A, Vol. 18(4). pp. 1287-1296. American Vacuum Society.
SRG	Jensen, Alan, Peter Renteln, Stephen Jew, Chris Raeder, and Patrick Cheung. June 2001. "Empirical-Based Modeling for Control of CMP Removal Uniformity." Solid State Technology, Vol. 44, No. 6, pp. 101-102, 104, 106. Cowan Publ. Corp.: Washington, D.C.
SRG	Sarfaty, Moshe, Arulkumar Shanmugasundram, Alexander Schwarm, Joseph Paik, Jimin Zhang, Rong Pan, Martin J. Seamons, Howard Li, Raymond Hung, and Suketu Parikh. April/May 2002. "Advance Process Control Solutions for Semiconductor Manufacturing." IEEE/SEMI Advanced Semiconductor Manufacturing Conference. pp. 101-106.
SRG	October 4, 2002. International Search Report from PCT/US01/22833.
SRG	October 23, 2002. International Search Report from PCT/US01/27406.
SRG	November 7, 2002. International Search Report from PCT/US02/19061.
SRG	November 11, 2002. International Search Report from PCT/US02/19117.
SRG	November 12, 2002. International Search Report from PCT/US02/19063.

EXAMINER 	DATE CONSIDERED <b>9/16/04</b> <b>5/28/03</b>
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				APPLICANT John F. ARACKAPARAMBIL et al.				Technology Center 2100	
				FILING DATE July 29, 1999		GROUP 2125			
U.S. PATENT DOCUMENTS									
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE			
SMB	3,767,900	10/23/73	Chao et al.			06/23/71			
SMB	3,920,965	11/18/75	Sohrwardy			03/04/74			
SMB	4,368,510	01/11/83	Anderson			10/20/80			
SMB	4,616,308	10/07/86	Morshedi et al.			12/02/85			
SMB	4,663,703	05/05/87	Axelby et al.			10/02/85			
SMB	5,347,446	09/13/94	Iino et al.			02/10/92			
SMB	5,519,605	05/21/96	Cawlfeld			10/24/94			
SMB	6,128,016	10/03/00	Coelho et al.			12/20/96			
SMB	6,219,711	04/17/01	Chari			10/01/97			
SMB	6,249,712	06/19/01	Boiquaye			09/25/96			
SMB	6,278,899	08/21/01	Piche et al.			10/06/98			
SMB	2001/0039462	11/08/01	Mendez et al.			04/02/01			
SMB	2001/0040997	11/15/01	Tsap et al.			05/15/01			
SMB	2002/0128805	09/12/02	Goldman et al.			12/26/00			
FOREIGN PATENT DOCUMENTS									
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation			
						Yes	No		
SMB	EP 1 067 757	01/10/01	Europe			X			
SMB	WO 01/33277	05/10/01	WO			X			
SMB	WO 02/31613 A2	04/18/02	WO			X			
SMB	WO 02/31613 A3	04/18/02	WO			X			
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)									
SMB	Levine, Martin D. 1985. <i>Vision in Man and Machine</i> . New York: McGraw-Hill, Inc. pp. ix-xii, 1-58.								
SMB	Pilu, Maurizio. September 2001. "Undoing Page Curl Distortion Using Applicable Surfaces." <i>IEEE International Conference on Image Processing</i> . Thessalonica, Greece.								
SMB	23 May 2003. Written Opinion for PCT/US01/24910.								
EXAMINER				DATE CONSIDERED					
Garley				9/16/04					

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ATTY. DOCKET NO.  
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APPLICANT  
John F. ARACKAPARAMBIL et al.

Technology Center 2100

FILING DATE  
July 29, 1999

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2125

U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
sn0	5,901,313	05/04/99	Wolf et al.			09/02/97
sn0	6,002,989	12/14/99	Shiba et al.			04/01/97
sn0	6,094,688	07/25/00	Mellen-Garnett et al.			03/12/98
sn0	6,340,602	01/22/02	Johnson et al.			02/12/01
sn0	6,345,288	02/05/02	Reed et al.			05/15/00
sn0	6,368,879	04/09/02	Toprac			09/22/99
sn0	US-2002/0107604	08/08/02	Riley et al.			12/06/00
sn0	6,470,230	10/22/02	Toprac et al.			01/04/00
sn0	6,482,660	11/19/02	Conchieri et al.			03/19/01
sn0	6,567,717	05/20/03	Krivokapic et al.			01/19/00

FOREIGN PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
sn0	WO 99/59200	11/18/99	WIPO			X	
sn0	WO 01/52319	07/19/01	WIPO			X	

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

sn0	Williams, Randy, Dadi Gudmundsson, Kevin Monahan, Raman Nurani, Meryl Stoller and J. George Shanthikumar. October 1999. "Optimized Sample Planning for Wafer Defect Inspection," <i>Semiconductor Manufacturing Conference Proceedings, 1999 IEEE International Symposium on Santa Clara, CA</i> . Piscataway, NJ. pp. 43 - 46.
sn0	23 July 2003. Invitation to Pay Additional Fees and Communication Relating to the Results of the Partial International Search for PCT/US02/19116.
sn0	01 August 2003. Written Opinion for PCT/US01/27406.
sn0	20 August 2003. Written Opinion for PCT/US01/22833.

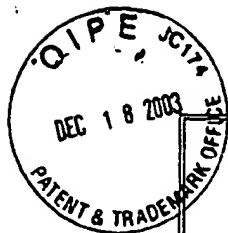
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SHEET 1 OF 2

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INFORMATION DISCLOSURE  
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004066  
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APPLICANT  
John F. ARACKAPARAMBIL et al.

FILING DATE  
July 29, 1999

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U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
snb	4,207,520	06/10/80	Flora et al.			04/06/78
snb	4,209,744	06/24/80	Gerasimov et al.			03/27/78
snb	4,609,870	09/02/86	Lale et al.			09/13/84
snb	4,755,753	07/05/88	Chern			07/23/86
snb	5,427,878	06/27/95	Corliss			05/16/94
snb	5,534,289	07/09/96	Bilder et al.			01/03/95
snb	5,867,389	02/02/99	Hamada et al.			11/26/96
snb	6,041,263	03/21/00	Boston et al.			10/01/97
snb	6,077,412	06/20/00	Ting et al.			10/30/98
snb	6,271,670	08/07/01	Caffey			02/08/99
snb	6,400,162	06/04/02	Mallory et al.			07/21/00
snb	US 2002/0077031	06/20/02	Johansson et al.			07/06/01
snb	6,442,496	08/27/02	Pasady et al.			08/08/00
snb	6,563,308	05/13/03	Nagano et al.			03/27/01
snb	6,587,744	07/01/03	Stoddard et al.			06/20/00

FOREIGN PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
snb	WO 01/11679	02/15/01	WIPO			X	
snb	WO 01/080306	10/25/01	WIPO			X	

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

snb	Miller, G. L., D. A. H. Robinson, and J. D. Wiley. July 1976. "Contactless measurement of semiconductor conductivity by radio frequency-free-carrier power absorption." <i>Rev. Sci. Instrum.</i> , Volume 47, No. 7. pp. 799 - 805.
snb	1999. "Contactless Bulk Resistivity/Sheet Resistance Measurement and Mapping Systems." <a href="http://www.Lehighton.com/fabtech1/index.html">www.Lehighton.com/fabtech1/index.html</a> .
snb	2000. "Microsense II Capacitance Gaging System." <a href="http://www.adetech.com">www.adetech.com</a> . 2000.

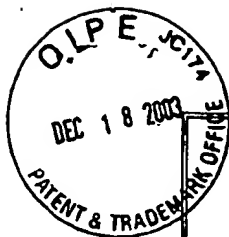
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9/16/04

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# 34

SHEET 2 OF 2

INFORMATION DISCLOSURE  
CITATION IN AN  
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ATTY. DOCKET NO.  
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09363, 966

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APPLICANT  
John F. ARACKAPARAMBIL et al.

FILING DATE  
July 29, 1999

GROUP  
2125


## FOREIGN PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No

## OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

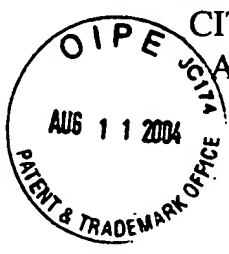
snv	El Chemali, Chadi et al. July/August 2000. "Multizone uniformity control of a chemical mechanical polishing process utilizing a pre- and postmeasurement strategy." J. Vac. Sci. Technol. Volume 18, No. 4. pp. 1287 - 1296, July/August 2000.
snb	March 5, 2001. "KLA-Tencor Introduces First Production-worthy Copper CMP In-situ Film Thickness and End-point Control System." <a href="http://www.kla-tencor.com/j/servlet/NewsItem?newsItemID=74">http://www.kla-tencor.com/j/servlet/NewsItem?newsItemID=74</a> .
snv	2002. "Microsense II - 5810: Non-Contact Capacitance Gaging Module." <a href="http://www.adetech.com">www.adetech.com</a> .
snv	08 August 2003. PCT International Search Report from PCT/US03/08513.
snb	14 October 2003. PCT International Search Report from PCT/US02/21942.
snb	20 October 2003. PCT International Search Report from PCT/US02/19116.
snv	23 October 2003. PCT International Preliminary Examination Report from PCT/US01/24910.
snl	"NanoMapper wafer nanotopography measurement by ADE Phase Shift." <a href="http://www.phase-shift.com/nanomap.shtml">http://www.phase-shift.com/nanomap.shtml</a> . 12/9/03
snb	"Wafer flatness measurement of advanced wafers." <a href="http://www.phase-shift.com/wafer-flatness.shtml">http://www.phase-shift.com/wafer-flatness.shtml</a> . 12/9/03
snb	"ADE Technologies, Inc.: 6360." <a href="http://www.adetech.com/6360.shtml">http://www.adetech.com/6360.shtml</a> . 12/9/03
snb	"3D optical profilometer MicroXAM by ADE Phase Shift." <a href="http://www.phase-shift.com/microxam.shtml">http://www.phase-shift.com/microxam.shtml</a> . 12/9/03
snv	"NanoMapper FA factory automation wafer nanotopography-measurement." <a href="http://www.phase-shift.com/nanomapperfa.shtml">http://www.phase-shift.com/nanomapperfa.shtml</a> . 12/9/03
EXAMINER	DATE CONSIDERED
Boled	9/10/04

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<b>U.S. PATENT DOCUMENTS</b>							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
SAE	4,901,218	02/13/90	Cornwell			03/04/88	
SAE	4,957,605	09/18/90	Hurwitt et al.			04/17/89	
SAE	5,240,552	08/31/93	Yu et al.			12/11/91	
SAE	5,369,544	11/29/94	Mastrangelo			04/05/93	
SAE	5,427,878	06/27/95	Corliss			05/16/94	
SAE	5,444,837	08/22/95	Bomans et al.			12/29/93	
SAE	5,665,214	09/09/97	Iturralde			05/03/95	
SAE	5,695,810	12/09/97	Dubin et al.			11/20/96	
SAE	5,761,065	06/02/98	Kittler et al.			03/30/95	
SAE	5,824,599	10/20/98	Schacham-Diamond et al.			01/16/96	
SAE	5,825,356	10/20/98	Habib et al.			03/18/96	
SAE	5,831,851	11/03/98	Eastburn et al.			03/21/95	
SAE	5,838,951	11/17/98	Song			08/28/96	
SAE	5,859,777	01/12/99	Yokoyama et al.			05/13/97	
SAE	5,862,054	01/19/99	Li			02/20/97	
SAE	5,871,805	02/16/99	Lemelson			04/08/96	
SAE	5,912,678	06/15/99	Saxena et al.			04/14/97	
SAE	5,926,690	07/20/99	Toprac et al.			05/28/97	
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SAE	6,012,048	01/04/00	Gustin et al.			05/30/97	
SAE	6,037,664	03/14/00	Zhao et al.			03/31/98	
SAE	6,059,636	05/09/00	Inaba et al.			07/09/98	
SAE	6,074,443	06/13/00	Venkatesh et al.			01/29/98	
SAE	6,096,649	08/01/00	Jang			10/25/99	
SAE	6,100,195	08/08/00	Chan et al.			12/28/98	
SAE	6,111,634	08/29/00	Pecen et al.			05/28/97	
SAE	6,114,238	09/05/00	Liao			05/20/98	
SAE	6,150,270	11/21/00	Matsuda et al.			01/07/99	
SAE	6,150,664	11/21/00	Su			06/29/99	
EXAMINER <i>Barb</i>			DATE CONSIDERED <i>9/16/04</i>				

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<b>INFORMATION DISCLOSURE</b> <b>CITATION IN AN APPLICATION</b> <b>(PTO-1449)</b>				ATTY. DOCKET NO. 004066 USA/Consilium/Consilium		SERIAL NO. 09/363,966	
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
SNL	6,157,864	12/05/00	Schwenke et al.			05/08/98	
SNL	6,181,013 B1	01/30/01	Liu et al.			03/13/00	
SNL	6,212,961 B1	04/10/01	Dvir			02/11/99	
SNL	6,226,563 B1	05/01/01	Lim			09/04/98	
SNL	6,228,280 B1	05/08/01	Li et al.			05/06/98	
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SNL	6,317,643 B1	11/13/01	Dmochowski			03/31/99	
SNL	2001/0044667 A1	11/22/01	Nakano et al.			05/16/01	
SNL	6,339,727 B1	01/15/02	Ladd			12/21/98	
SNL	6,346,426 B1	02/12/02	Toprac et al.			11/17/00	
SNL	6,355,559 B1	03/12/02	Havemann et al.			11/03/00	
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SNL	6,432,728 B1	08/13/02	Tai et al.			10/16/00	
SNL	6,442,496 B1	08/27/02	Pasady et al.			08/08/00	
SNL	6,449,524 B1	09/10/02	Miller et al.			01/04/00	
SNL	6,455,415 B1	09/24/02	Lopatin et al.			04/16/01	
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SNL	6,484,064 B1	11/19/02	Campbell			10/05/99	
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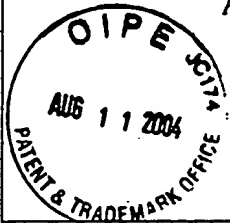
2/1/04

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# 32

INFORMATION DISCLOSURE  
CITATION IN AN  
APPLICATION  
(PTO-1449)



ATTY. DOCKET NO.  
004066  
USA/Consilium/Consilium

SERIAL NO.  
09/363,966

APPLICANT  
John F. ARACKAPARAMBIL et al.

FILING DATE  
July 29, 1999

GROUP  
2125

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SR6	EP 1 083 470 A2	03/14/01	EP			X	
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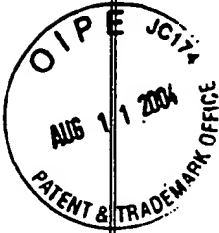
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<b>INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)</b>		ATTY. DOCKET NO. 004066 USA/Consilium/Consilium	SERIAL NO. 09/363,966 <b>RECEIVED</b> AUG 13 2004
		APPLICANT John F. ARACKAPARAMBIL Technology Center 2100	
		FILING DATE July 29, 1999	GROUP 2125
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